

# EUV ERLs for Semiconductor Integrated Circuits Lithography

Norio Nakamura

High Energy Accelerator Research Organization(KEK)

**ERL17, 18-23 June 2017, CERN, Geneva, Switzerland**



# EUV-ERL Design Group

---



(KEK) T. Furuya, K. Haga, I. Hanyu, K. Harada, T. Honda, Y. Honda, E. Kako, Y. Kamiya, R. Kato, H. Kawata, Y. Kobayashi, T. Konomi, T. Kubo, S. Michizono, T. Miura, T. Miyajima, H. Nakai, N. Nakamura, T. Obina, K. Oide, H. Sakai, M. Shimada, R. Takai, Y. Tanimoto, K. Tsuchiya, K. Umemori, S. Yamaguchi, M. Yamamoto



(QST) R. Hajima



(Tohoku Univ.) N. Nishimori

東北大学

The design study has been done under collaboration with a Japanese company.

# Outline

---

- Introduction
- Design of EUV ERL Source
- S2E Simulation
- Activities and Considerations for Industrialization
- Summary

# Outline

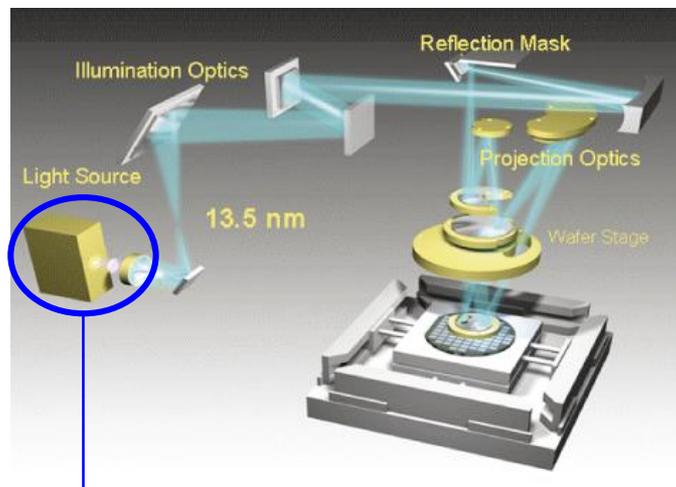
---

- Introduction
- Design of EUV ERL Source
- S2E Simulation
- Activities and Considerations for Industrialization
- Summary

# EUV Lithography

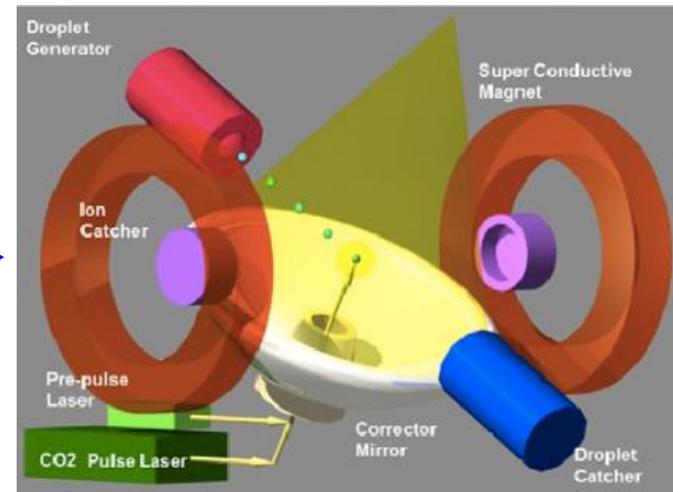
EUV Lithography :

- Next generation lithography using extreme ultraviolet light (13.5 nm)
- Allows exposure of fine circuit pattern with a half-pitch below 20 nm
- **Laser-produced plasma(LPP) source** is under development for  $\geq 250$  W



Schematic of EUV exposure tool

H. Mizoguchi et al., Komatsu Technical Report 59-166 (2013)



Concept of LPP EUV source

H. Mizoguchi et al., Proc. of SPIE 10143, 101431J (2017)

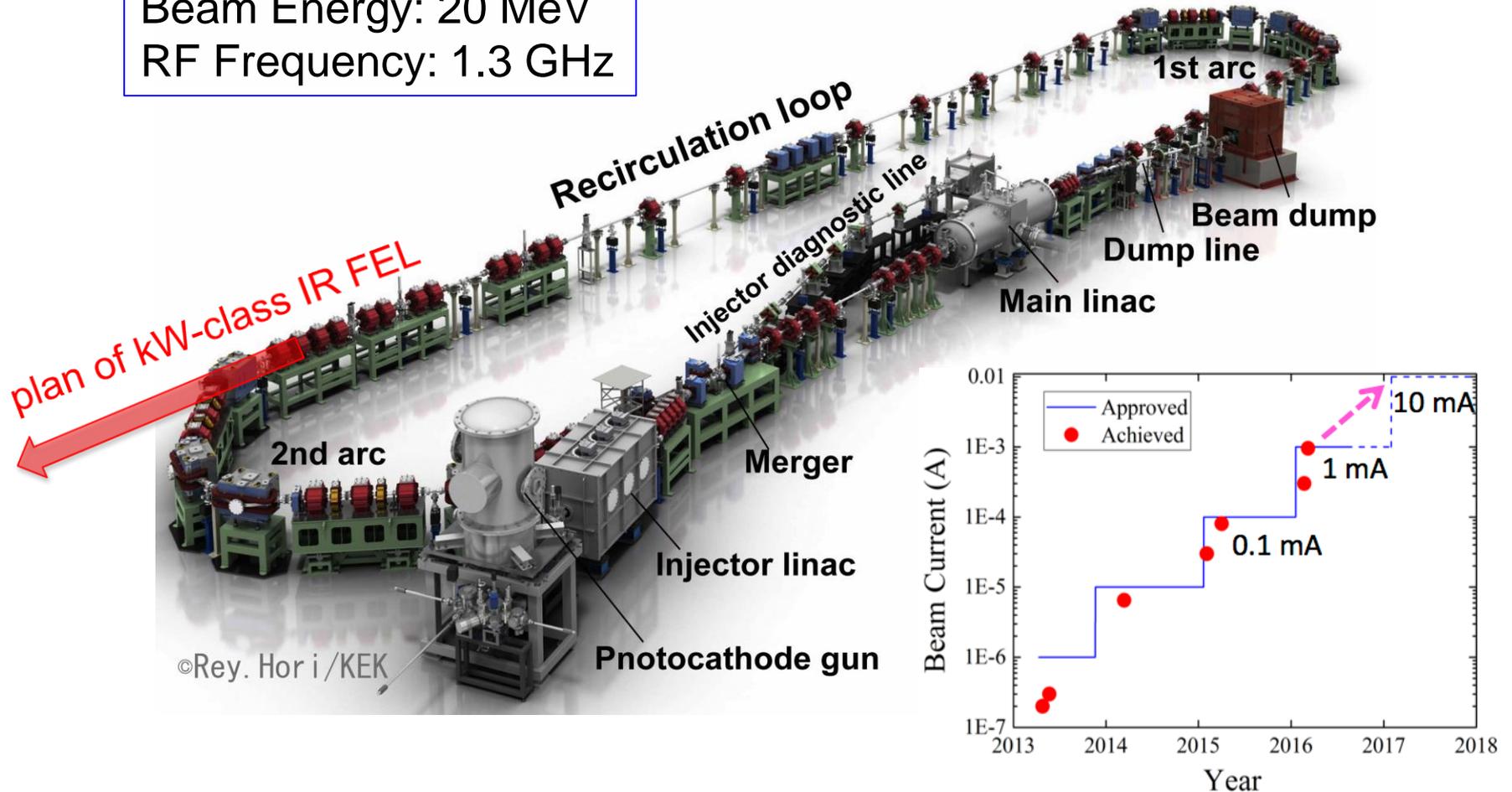
**EUV ERLs (EUV FEL sources based on ERLs)** ←-----

- Meet future demand for 1 kW EUV power or more
- Distribute 1-kW class power to multiple scanners → more economical
- Produce no debris contaminating the EUV optics
- Reduce dumped beam power and activation drastically

# Compact ERL(cERL)

in operation at KEK since 2013

Beam Energy: 20 MeV  
RF Frequency: 1.3 GHz



©Rey. Hor i /KEK

History of achieved beam current

cERL technologies and resources are available for EUV ERLs.

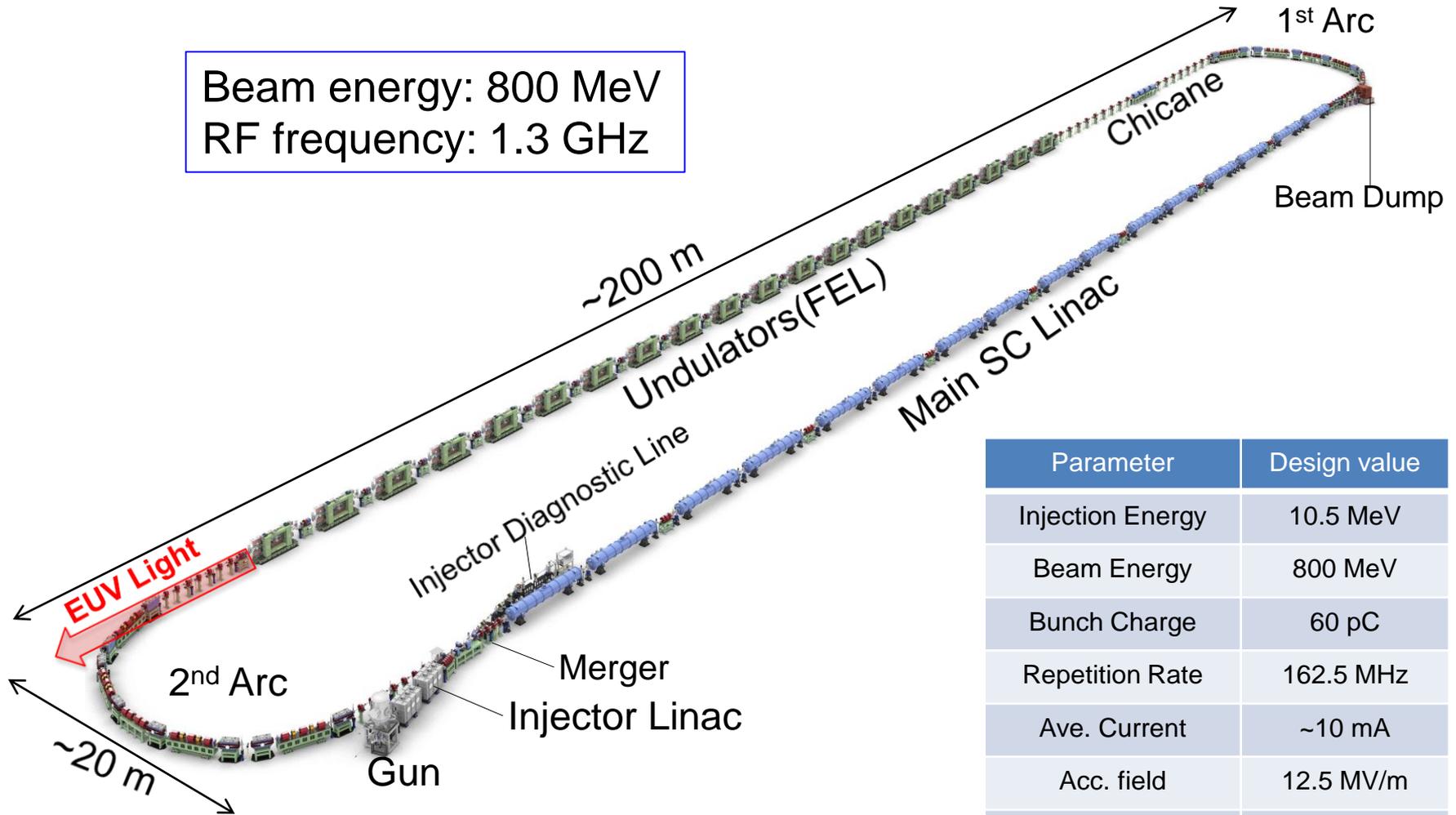
# Outline

---

- Introduction
- Design of EUV ERL Source
- S2E Simulation
- Activities and Considerations for Industrialization
- Summary

# Image of EUV-ERL Source

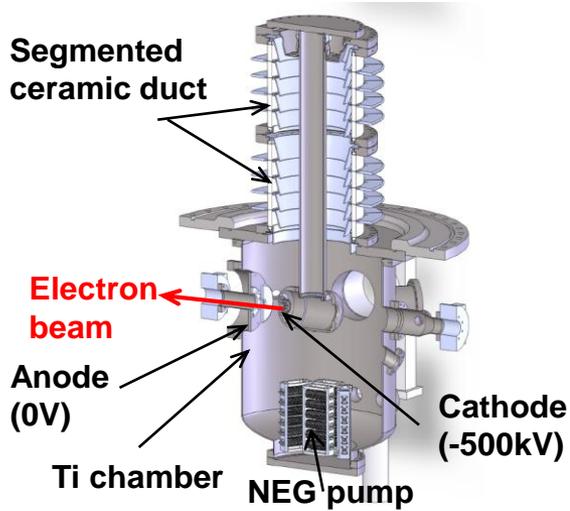
Beam energy: 800 MeV  
RF frequency: 1.3 GHz



Parameter	Design value
Injection Energy	10.5 MeV
Beam Energy	800 MeV
Bunch Charge	60 pC
Repetition Rate	162.5 MHz
Ave. Current	~10 mA
Acc. field	12.5 MV/m
EUV Wavelength	13.5 nm
EUV power	> 10 kW

©Rey.Hori/KEK

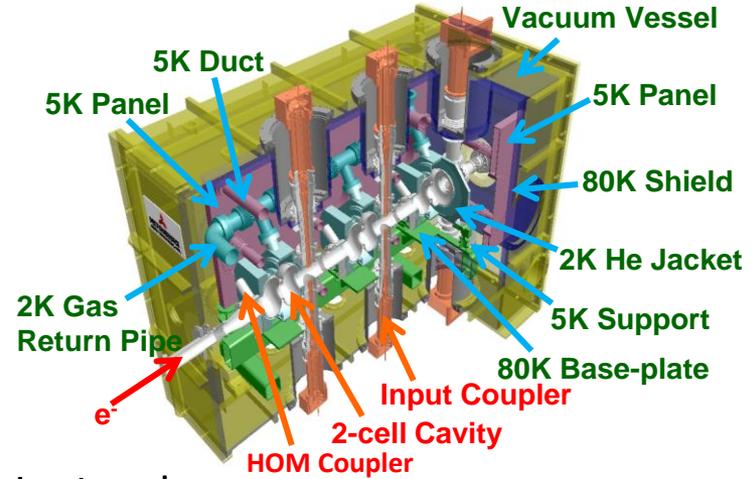
# Injector & Merger



**Photocathode DC gun**

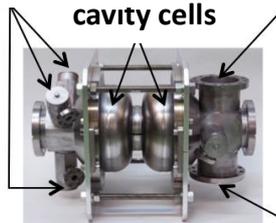


**cERL Injector cryomodule**

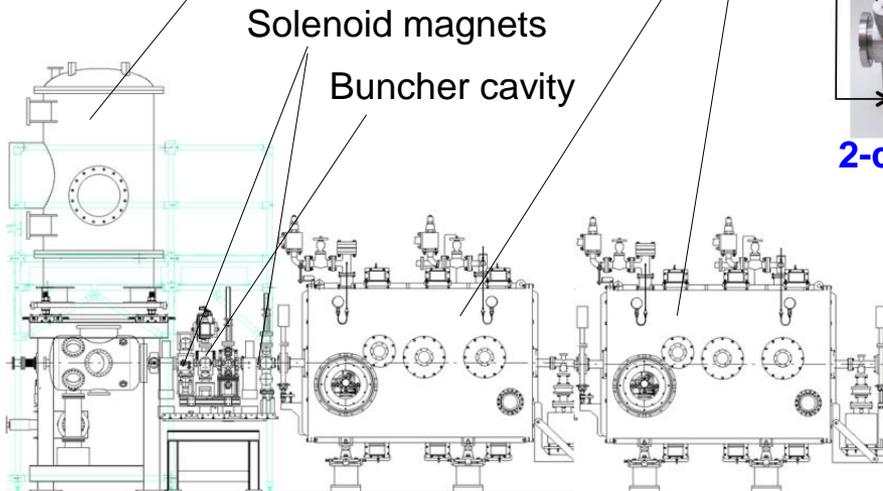


**Cryomodule design**

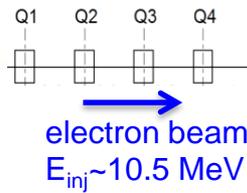
HOM coupler cavity cells Input coupler



**2-cell SC cavity**

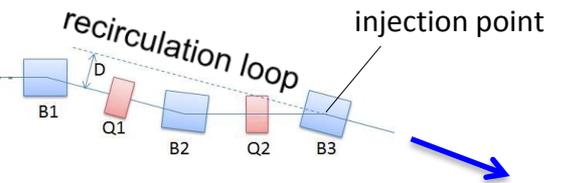


**Injector section (side view)**



**matching section**

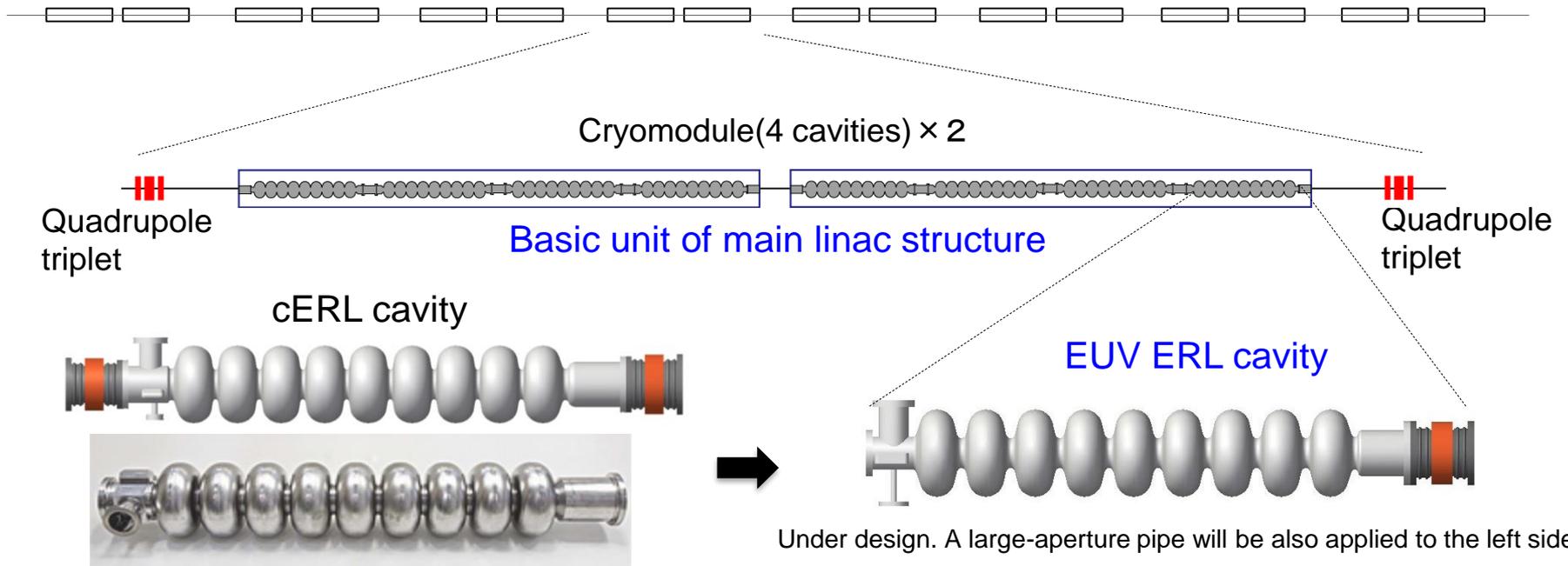
B : Bending magnets ( $\theta=15^\circ$  ,  $\rho=1\text{m}$ )  
Q : Quadrupole magnet



**Merger section (top view)**

# Main Linac

Main linac (9-cell cavities × 64 in 16 cryomodules)

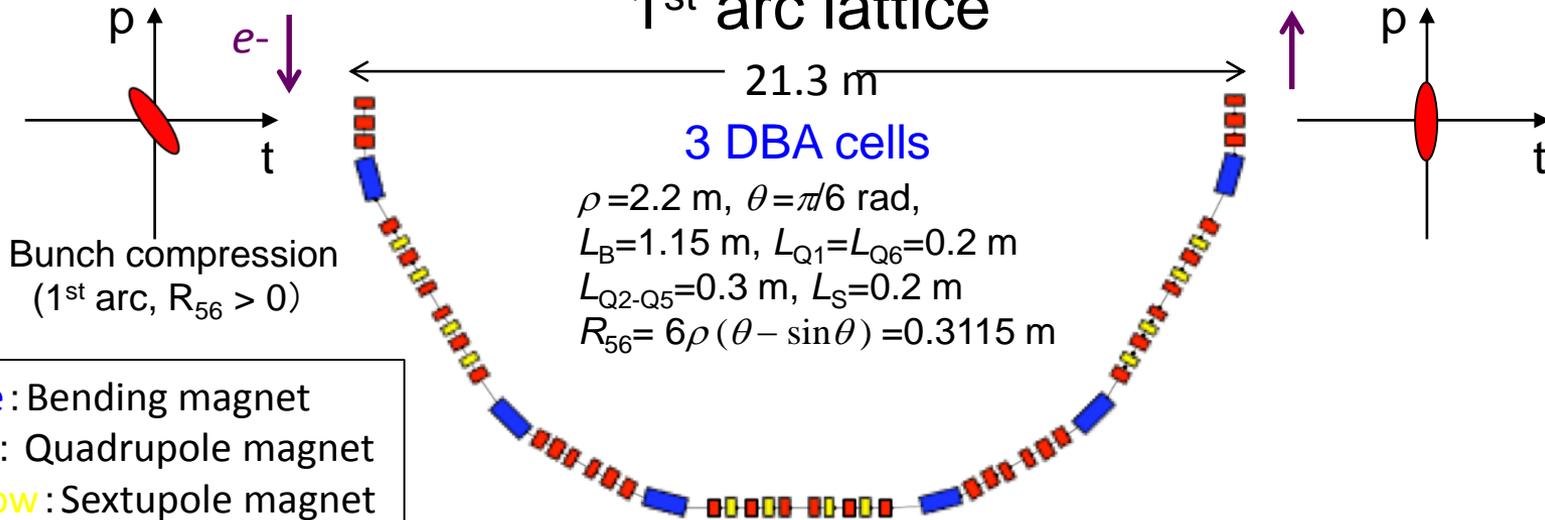


	cERL	EUV ERL		cERL	EUV ERL
Frequency	1.3 GHz	1.3 GHz	Iris diameter	80 mm	70 mm
$R_{sh}/Q$	897 $\Omega$	1007 $\Omega$	$Q_o \times R_s$	289 $\Omega$	272 $\Omega$
$E_p/E_{acc}$	3.0	<b>2.0</b>	$H_p/E_{acc}$	42.5 Oe/(MV/m)	42.0 Oe/(MV/m)

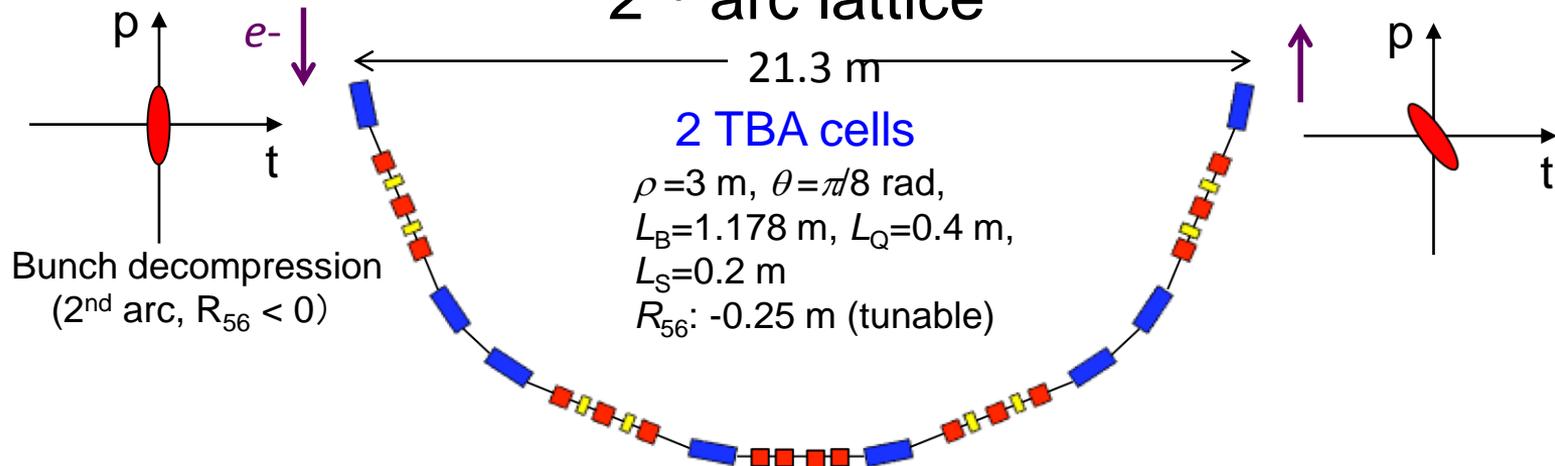
Stable operation at 8.5 MV/m (cERL) → **12.5 MV/m (EUV-ERL)**

# Arc Sections

## 1<sup>st</sup> arc lattice



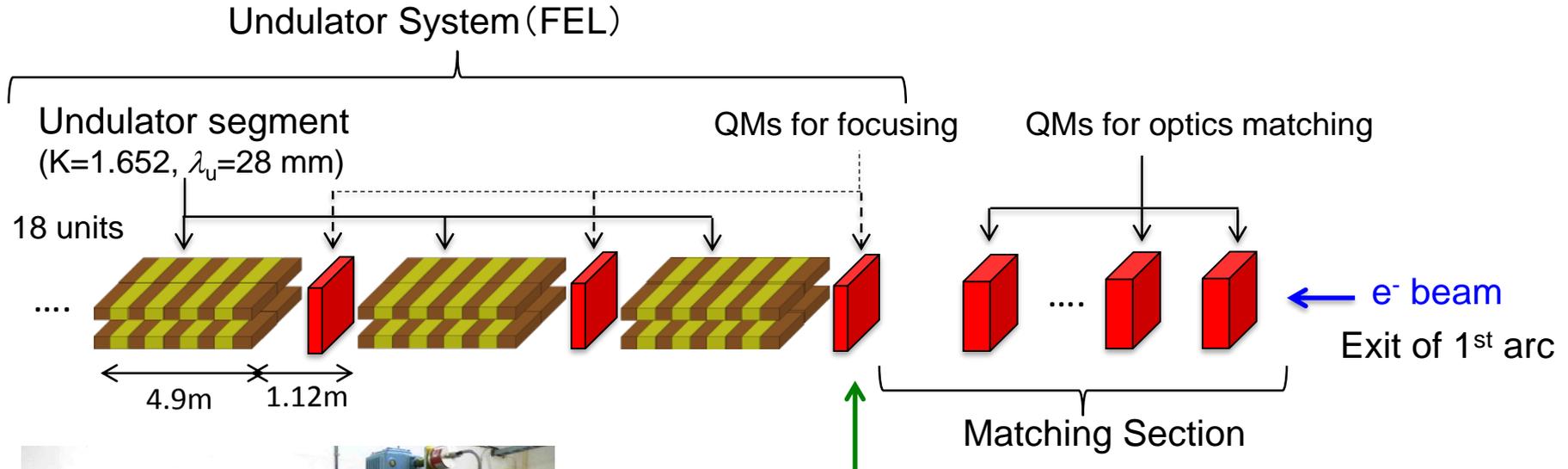
## 2<sup>nd</sup> arc lattice



Optics are optimized for bunch compression and decompression.

# Undulator System for FEL

## Undulator System (including matching section)



Adjustment of Twiss parameters  $\beta_{x,y}, \alpha_{x,y}$  @ FEL entrance for maximizing FEL output power



Circularly-polarizing undulator developed at KEK

- Parameters of undulator system to be optimized
- (1) Undulator period and K-value (magnetic gap)
  - (2) Segment length and gap between segments
  - (3) Magnetic strength of QMs for focusing
  - (4) Undulator tapering

# Outline

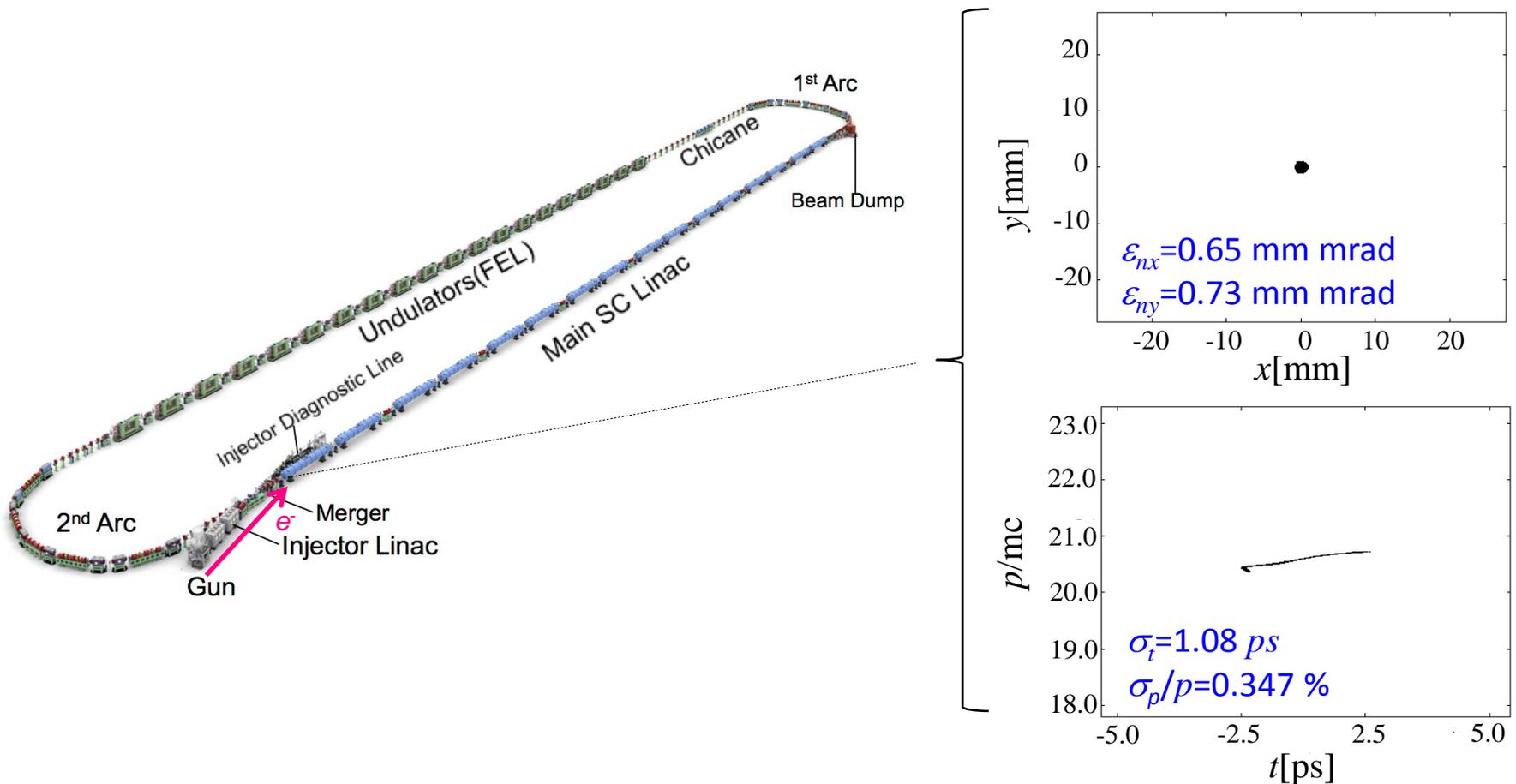
---

- Introduction
- Design of EUV ERL Source
- **S2E Simulation**
- Activities and Considerations for Industrialization
- Summary

# Injector & Merger

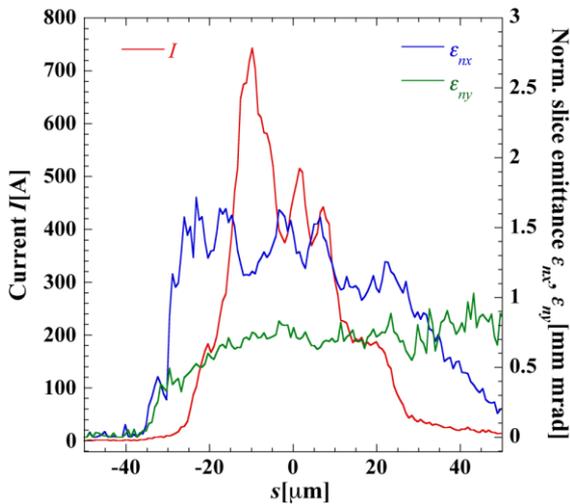
## Injection beam optimization by GPT and genetic algorithm

Bunch charge:  $Q_b=60$  pC, Injection energy:  $E_{inj}=10.5$  MeV, Bunch length:  $\sigma_t \sim 1$  ps



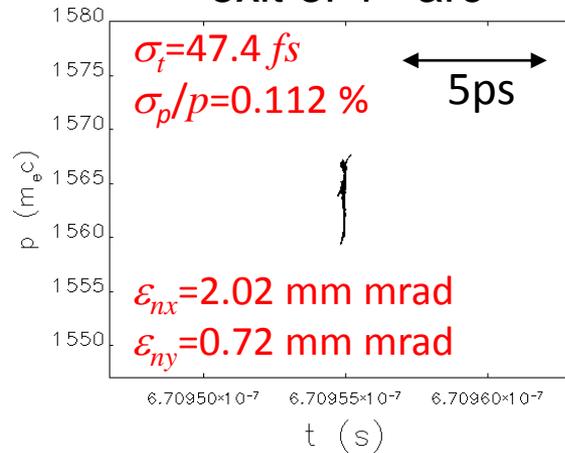
# Bunch Compression

Current & slice emittance

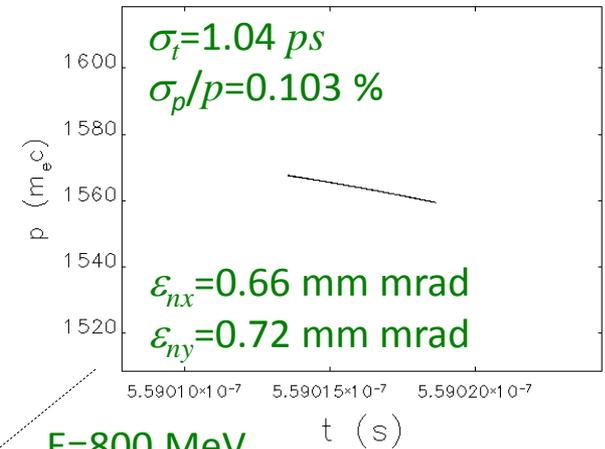


**Peak current  $I_p > 700$  A**  
**Slice  $\epsilon_{nx}/\epsilon_{ny} \approx 1.2/0.7$  mm mrad at  $I=I_p$**

exit of 1<sup>st</sup> arc

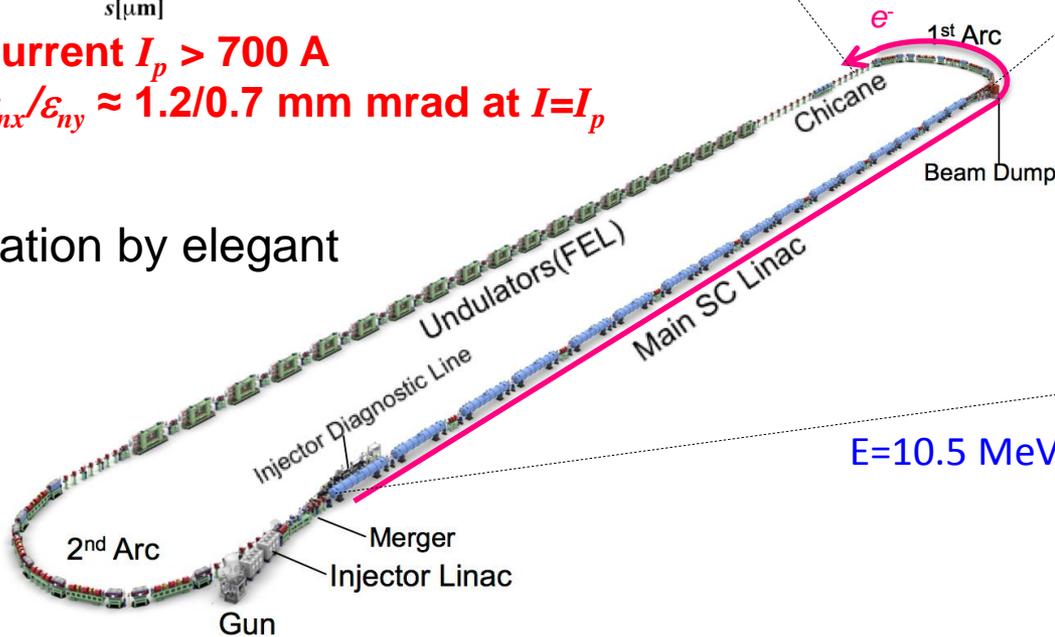


entrance of 1<sup>st</sup> arc

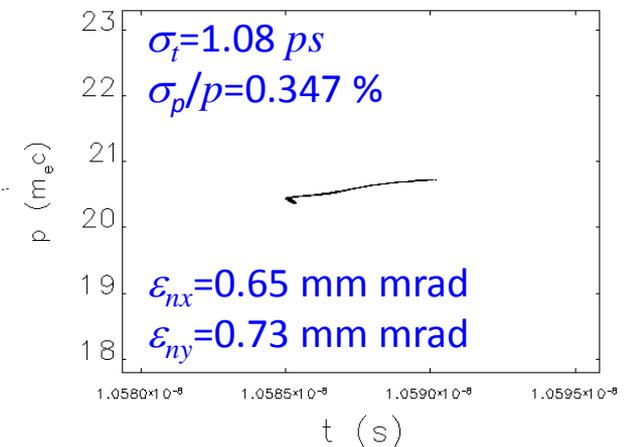


$E = 800$  MeV

simulation by elegant

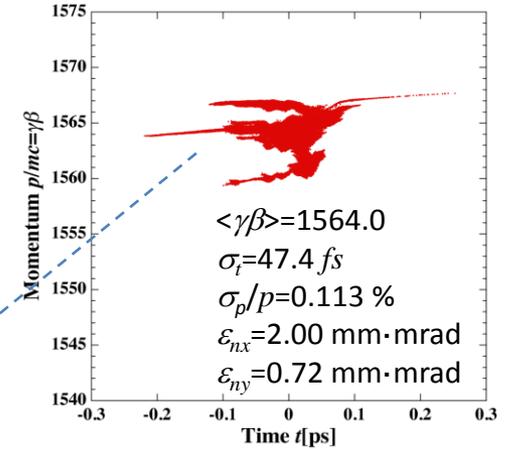
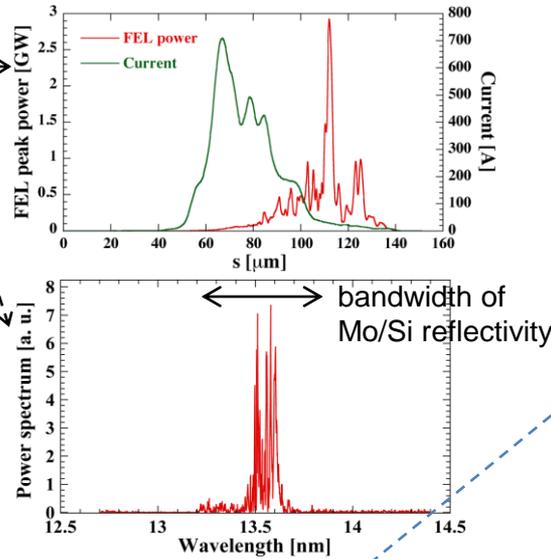
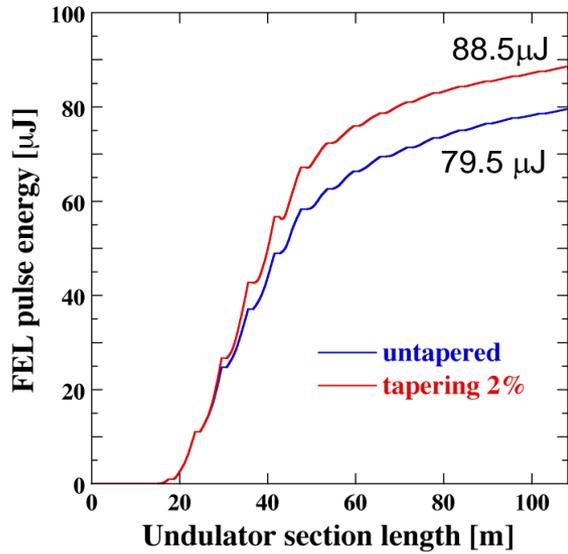


entrance of main linac



$E = 10.5$  MeV

# FEL



FEL power without tapering: 12.9/25.8 kW @ 9.75/19.5 mA (162.5/325 MHz)

FEL power with 2% tapering: 14.4/28.8 kW @ 9.75/19.5 mA (162.5/325 MHz)

( $P_{\text{FEL}}=88.5\ \mu\text{J} \times 162.5\ \text{MHz}=14.4\ \text{kW}$ ,  $I_{\text{av}}=60\text{pC} \times 162.5\ \text{MHz}=9.75\ \text{mA}$ )

Energy spread is increased.

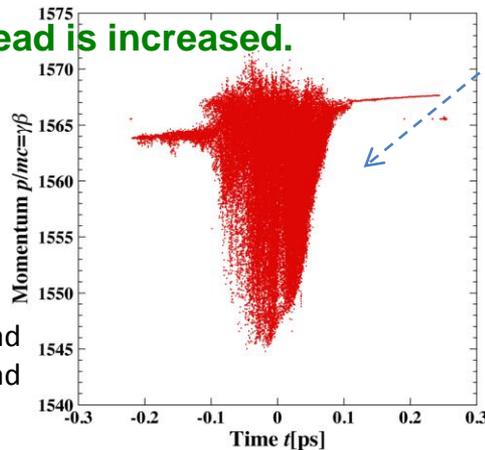
$\langle\gamma\beta\rangle=1561.1$

$\sigma_t=48.5\text{ fs}$

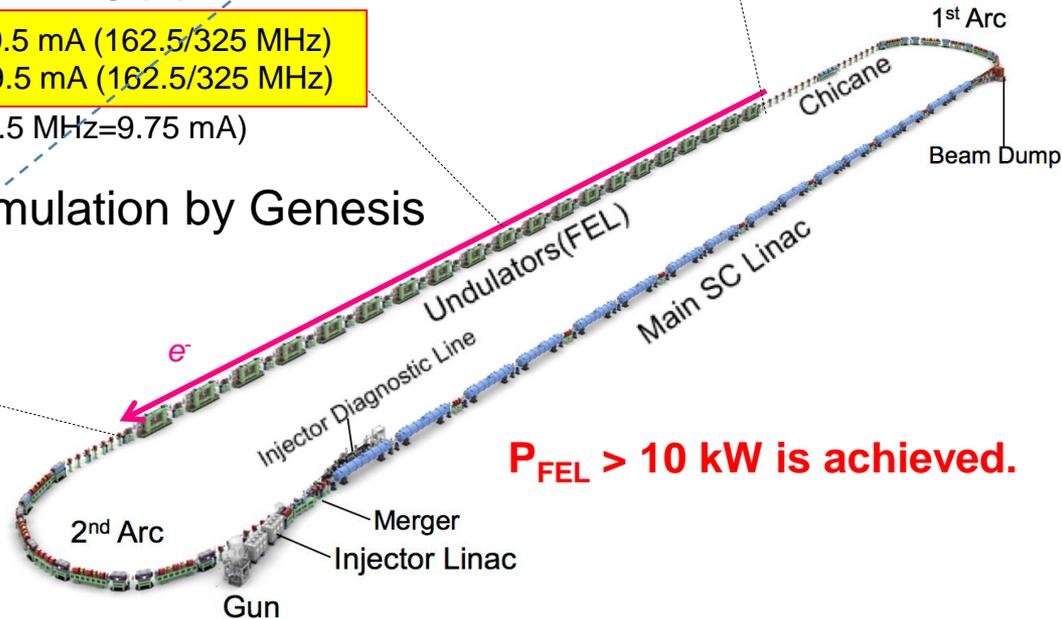
$\sigma_p/p=0.299\%$

$\varepsilon_{nx}=1.98\text{ mm}\cdot\text{mrad}$

$\varepsilon_{ny}=0.71\text{ mm}\cdot\text{mrad}$



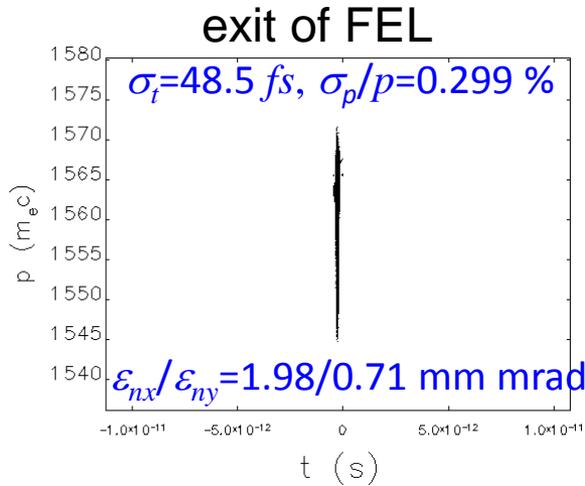
simulation by Genesis



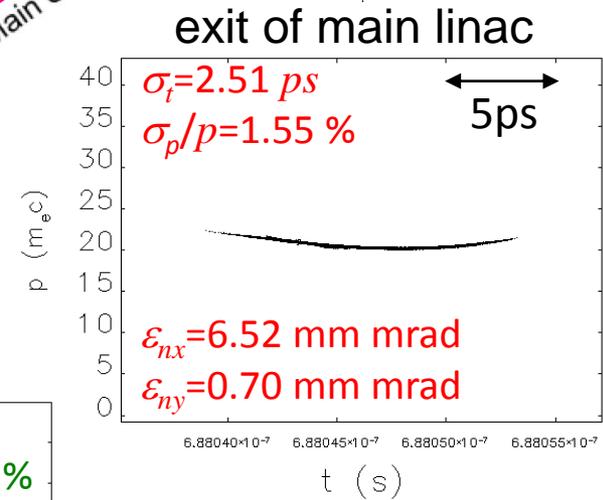
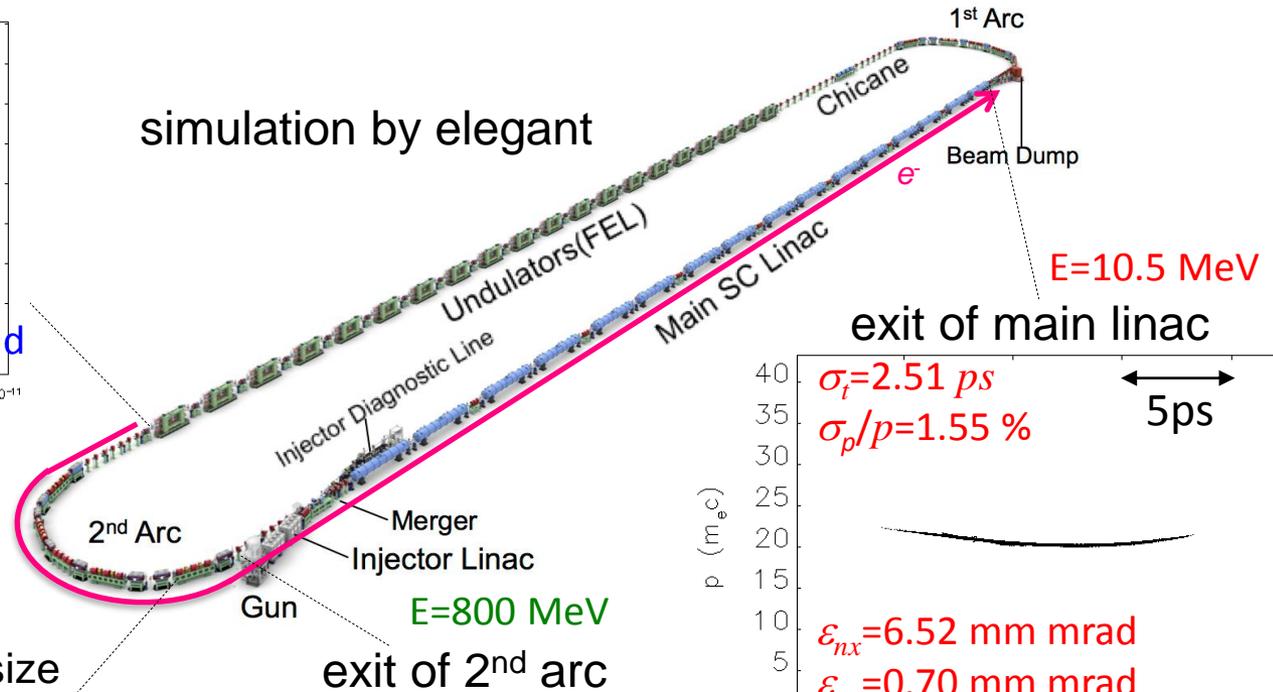
$P_{\text{FEL}} > 10\ \text{kW}$  is achieved.

# Bunch Decompression

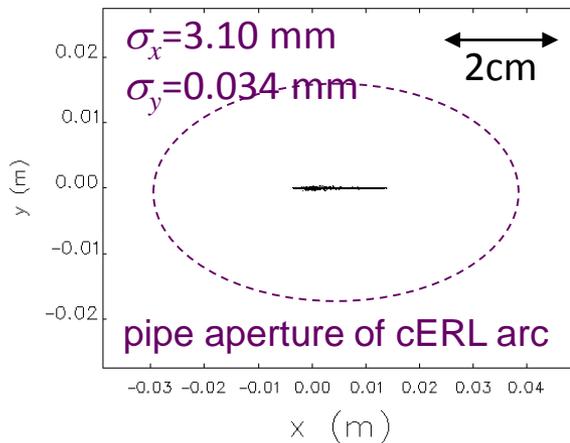
**Electron beam is transported without beam loss.**



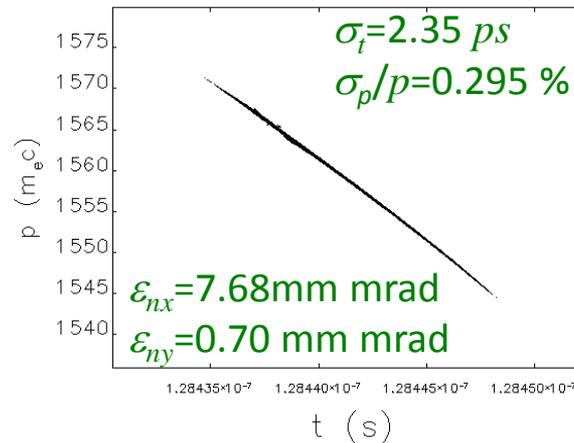
simulation by elegant



point of maximum beam size



exit of 2nd arc



# Outline

---

- Introduction
- Design of EUV ERL Source
- S2E Simulation
- **Activities and Considerations for Industrialization**
- Summary

# EUV-FEL Light Source Study Group for Industrialization

since 2015

 THE UNIVERSITY OF TOKYO  
S. Ishihara (Leader)

 THE UNIVERSITY OF TOKYO

 I. Matsuda

  
宇都宮大学  
UTSUNOMIYA UNIVERSITY

Utsunomiya Univ.  
T. Higashiguchi

Univ. of Hyogo  
H. Kinoshita

Waseda Univ.  
M. Washio

Osaka Univ.  
T. Kozawa

## Industries

**TOSHIBA**  
Leading Innovation >>>

 **MITSUBISHI HEAVY INDUSTRIES**  
MECHATRONICS SYSTEMS, LTD.

 **Hitachi Metals, Ltd.**  
Materials Magic

 **GIGAPHOTON**

 **EIDEC**

**TOYAMA**

Industrialization of High Power EUV light  
source based on ERL@KEK and FEL@QST

 **TAIYO NIPPON SAN SO**  
The Gas Professionals

**HITACHI**

**TOSHIBA**  
Leading Innovation >>>  
**TOSHIBA ELECTRON TUBES & DEVICES CO., LTD.**

 **MITSUBISHI**  
ELECTRIC  
Changes for the Better

 **NTTAT**

 R. Hajima

 H. Kawata et al.

 National Institute of  
Advanced Industrial Science  
and Technology  
**AIST** N. Sei

# EUV-FEL Workshop

Date: 13 Dec 2016 10:00-17:00

Site: Akihabara UDX 4F NEXT-1

Participants : > 100

(Source group, tool and material vendors, end users etc.)

URL: [http://pfwww.kek.jp/PEARL/EUV-FEL\\_Workshop/](http://pfwww.kek.jp/PEARL/EUV-FEL_Workshop/)



## EUV-FEL WORKSHOP

ワークショップ

# EUV-FEL WORKSHOP

加速器科学が拓く革新的イノベーション  
～半導体 LSI 製造プロセス用 EUV 光源をめざして～

**参加費 無料** 定員 120 名

開催 **2016 12.13** Tue 10:00-17:30

web 申込み先  
申込み締切 12月9日(金)まで  
  
[http://pfwww.kek.jp/PEARL/EUV-FEL\\_Workshop/](http://pfwww.kek.jp/PEARL/EUV-FEL_Workshop/)

開催場所  
秋葉原 UDX 4F 「NEXT-1」  
  
<http://www.udx-n.jp/access.html>

お問い合わせ  
高エネルギー加速器研究機構  
研究支援戦略推進部  
大学・産業連携推進室  
TEL.029-879-6239

基調講演  
「Big Data時代のCognitive Computingに向けたNeuromorphic Device」  
"Neuromorphic Device for Cognitive Computing in the Big Data era"  
日本アイ・ビー・エム(株) 東京基礎研究所 サイエンス&テクノロジー 部長 新川崎事業所長 **山道 新太郎 氏**  
IBM Japan Senior Manager Shintaro Yamamichi

招待講演  
「半導体集積回路の微細化とEUVリソグラフィ」  
"Scaling of Semiconductor Integrated Circuits and EUV Lithography"  
(株) 先端ナノプロセス基盤開発センター 代表取締役社長 **石内 秀美 氏**  
EIDEC President Hidemi Ishiuchi

「EUV Lithography Industrialization and future outlook」  
エーエスエムエル(株) テクノロジーデベロップメントセンター ディレクター **宮崎 順二 氏**  
ASML Japan Co.,Ltd. Director Junji Miyazaki

主催：EUV-FEL 光源産業化研究会、高エネルギー加速器研究機構 共催：産学技術総合研究所 後援：TIA



# Availability Issues

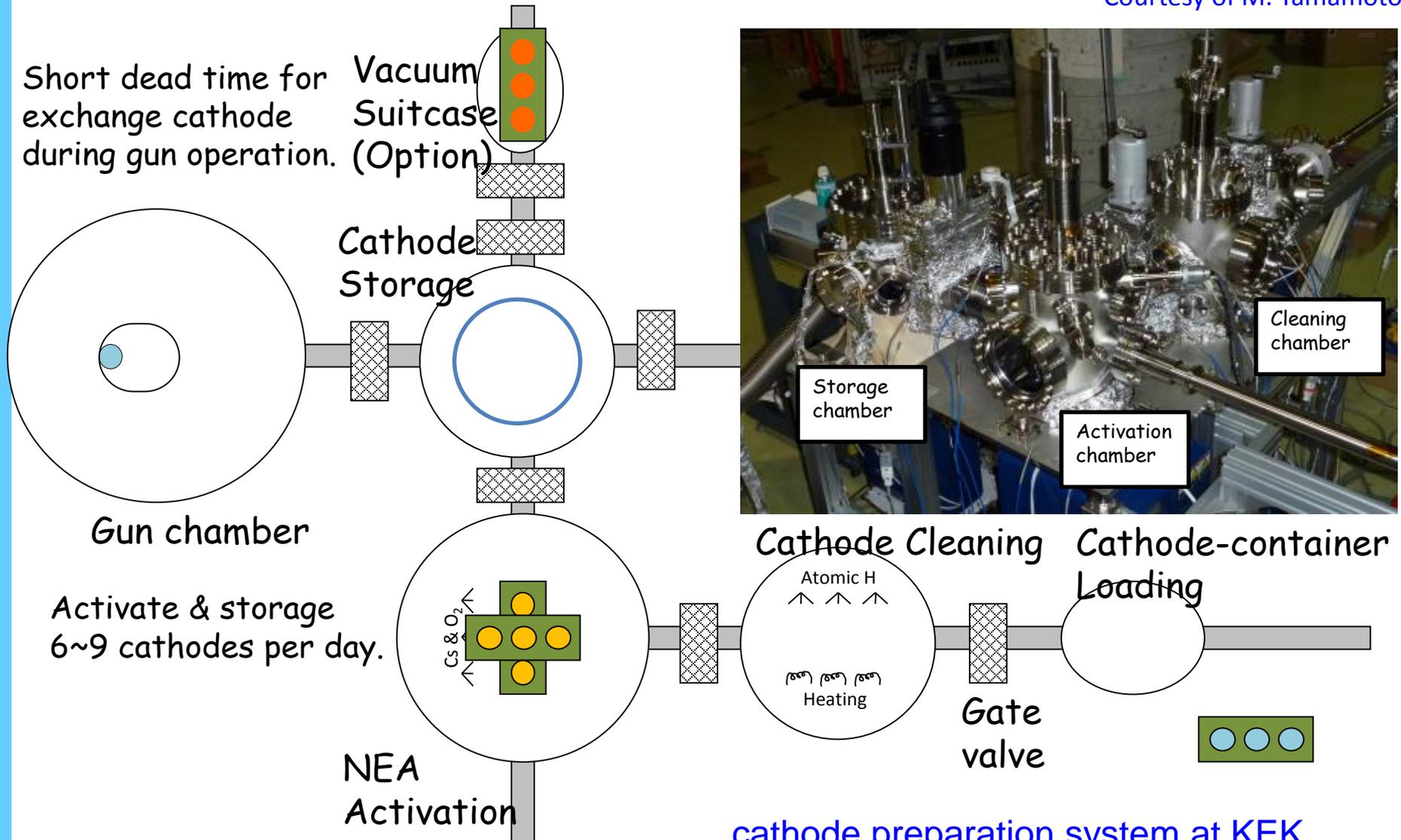
Required availability for industrialization:  $\geq 98\%$   
( non-operation time  $\leq \sim 1$  week per year)



- Electron gun
  - Short photocathode lifetime ( one week for  $\sim 10$  mA )
  - Remote control of photocathode exchange
- SC Cavity
  - Reduction of trip rate
  - Pulse processing time for suppression of field emission increase
- Undulator
  - Demagnetization of permanent magnets
- Cryoplant
  - High pressure gas safety law
  - Safety inspection (once per year in Japan)

# Cathode Preparation System

Courtesy of M. Yamamoto

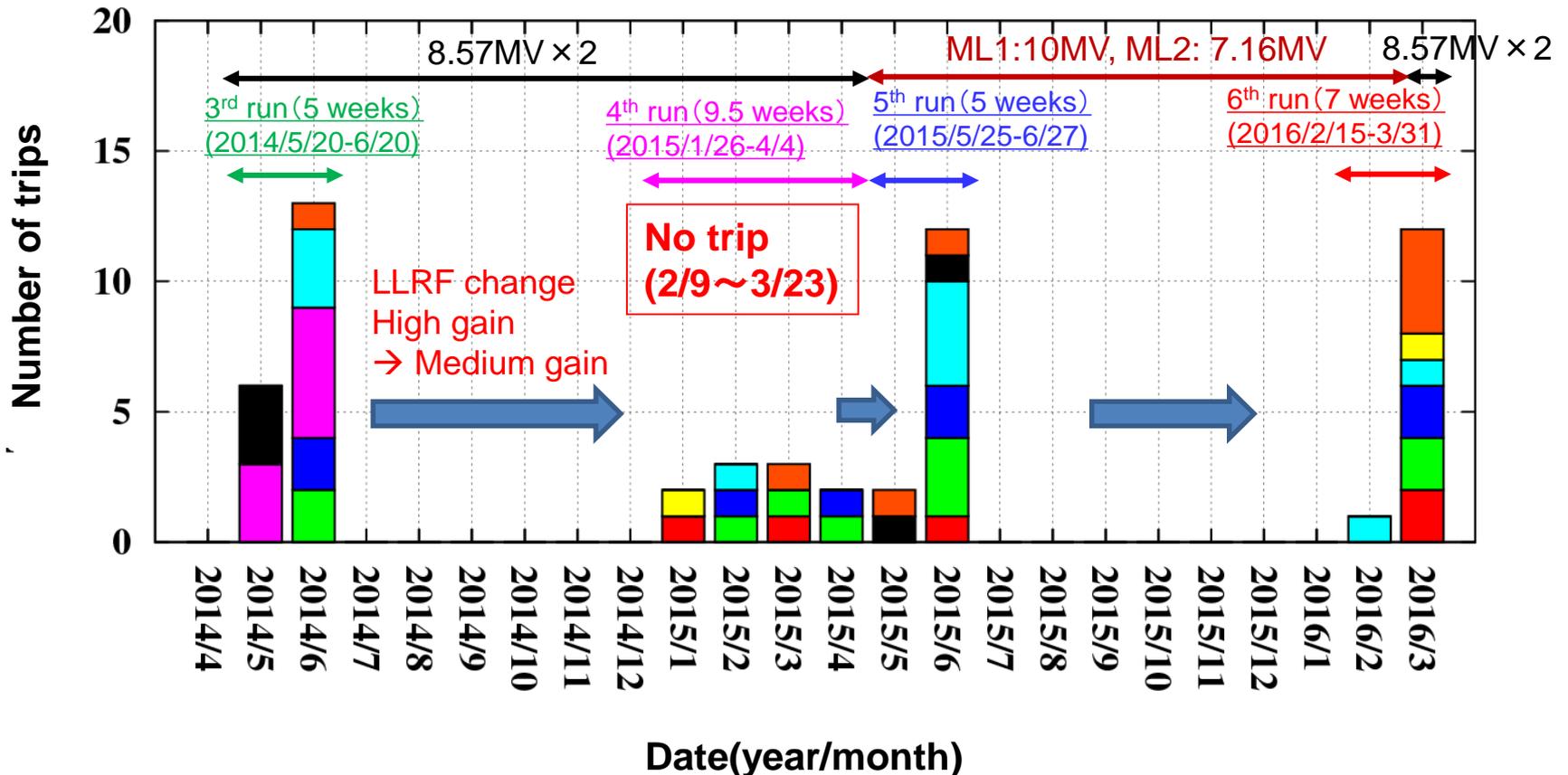


cathode preparation system at KEK

# Trip of SC Cavities

Trips of cEERL Main Linac Cavities

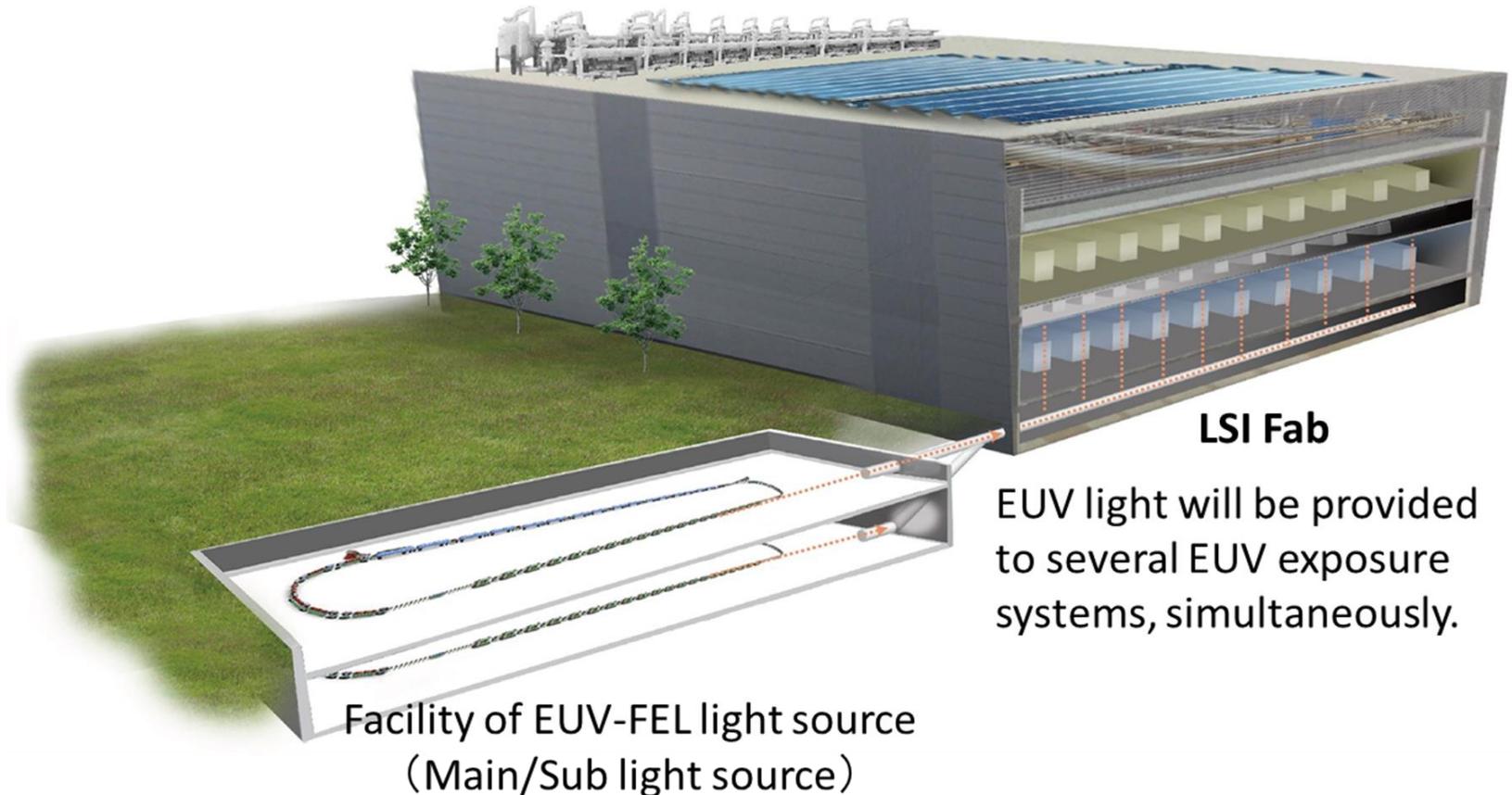
Courtesy of H. Sakai



# Redundant System

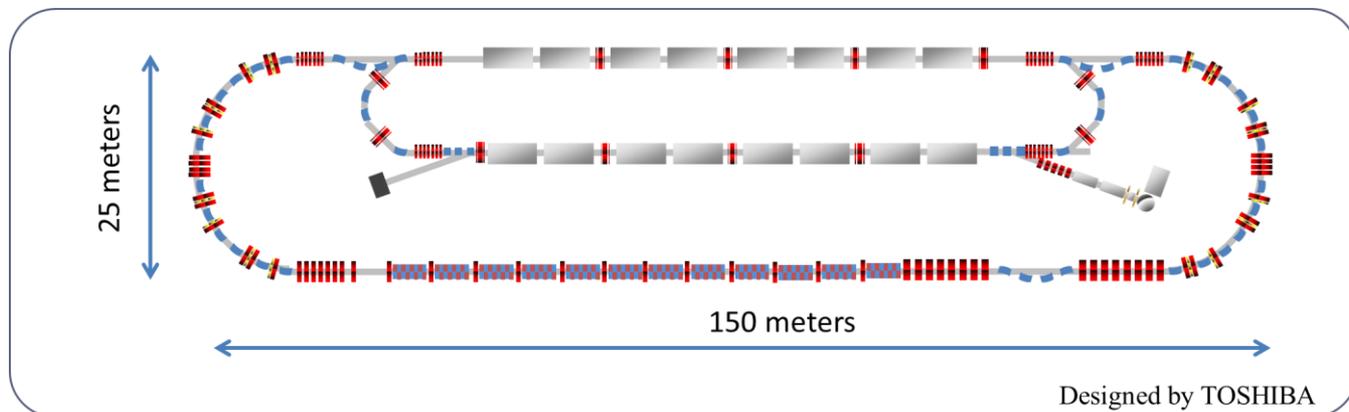
Redundant System for ensuring high availability

- Critical parts (Cryoplant, Injector, Main Linac, Undulator, ... )
- Entire light source system



# Reduction of Source Size

- Higher field gradient of Main SC cavities
  - Increase of power consumption  $\propto E_{\text{acc}}^2/Q$
  - High-Q SC cavity (Nitrogen doping etc.)
- Lower Beam Energy
  - Shorter-period undulator with strong magnetic field
  - Increase of current or energy conversion efficiency for the same FEL power
- 2-loop/2-turn ERL
  - Optics design for CSR effect suppression
  - Increase of current for the same FEL power



# Outline

---

- Introduction
- Design of EUV ERL Source
- S2E Simulation
- Activities and Considerations for Industrialization
- Summary

# Summary

---

- EUV ERLs are expected to be high-power EUV sources for lithography that meet future demand.
- An EUV ERL source has been designed with available technologies and resources and its performance has been checked by S2E simulation.
  - Generation of FEL power more than 10 kW at 10 mA in the designed EUV-ERL source
  - Successful transportation of electron beams throughout the EUV-ERL source without any beam loss
- We established the source group for industrialization and organized the EUV-FEL workshop. R&D efforts are required for industrialization to achieve high availability, size reduction and so on.

Thank you for your attention!



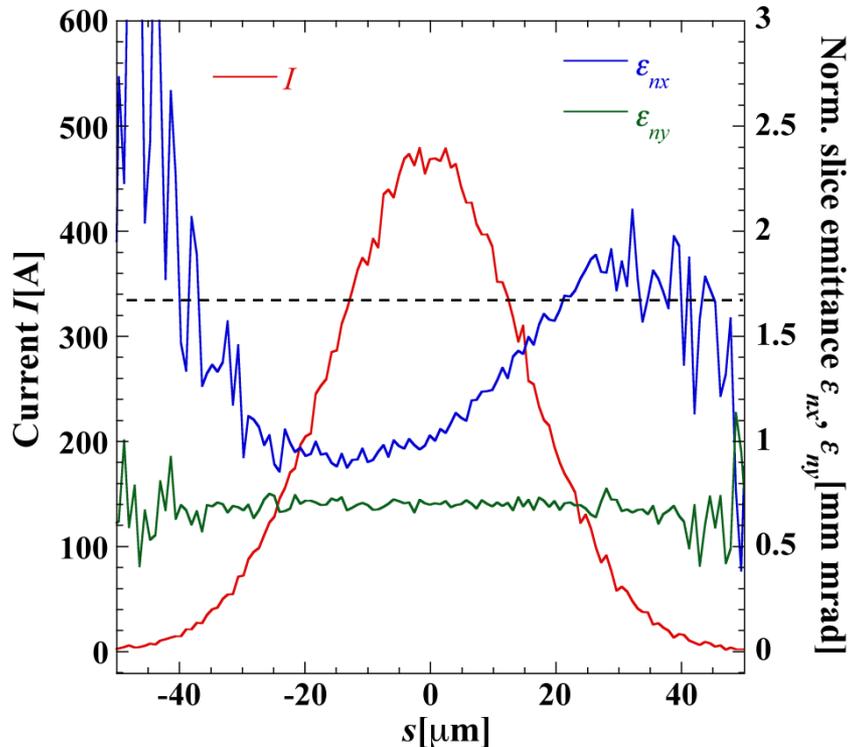
# Backup Slides

# Suppression of CSR effects

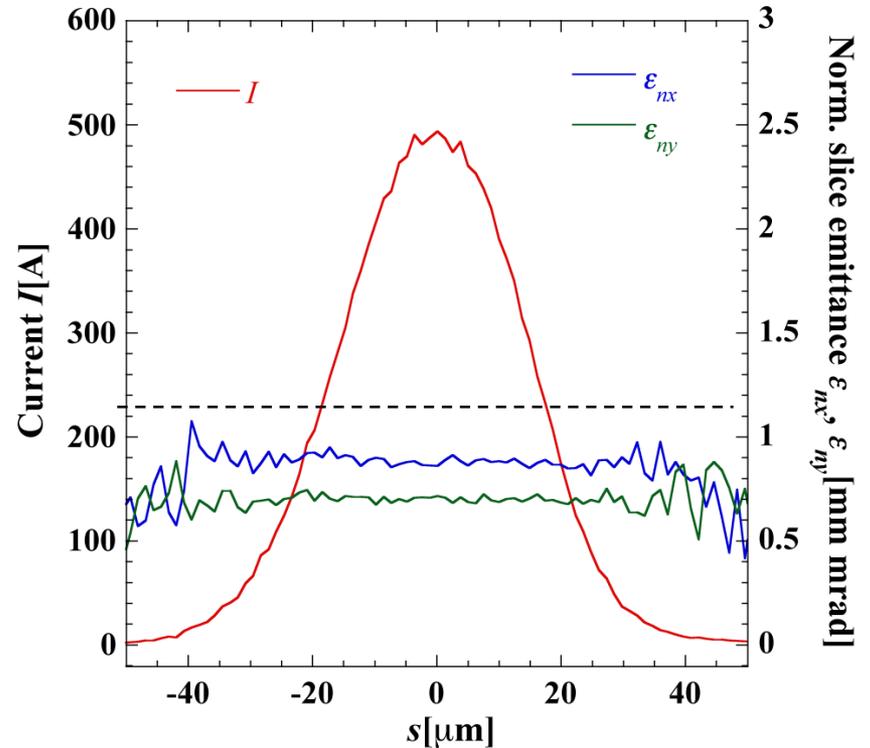
Electron distribution after bunch compression

Initial parameters:  $Q_b=60$  pC,  $\varepsilon_{nx}=\varepsilon_{ny}=0.7$  mm mrad,  $\sigma_p/p=0.31\%$ ,  $\sigma_{t,inj}=1$  ps (Gaussian beam)

TBA arc + chicane ( $R_{56}=-0.15/-0.15$  m)



DBA arc ( $R_{56}=0.31$  m,  $\beta_{x2}=0.5$  m,  $\alpha_{x2}=1.9$ )

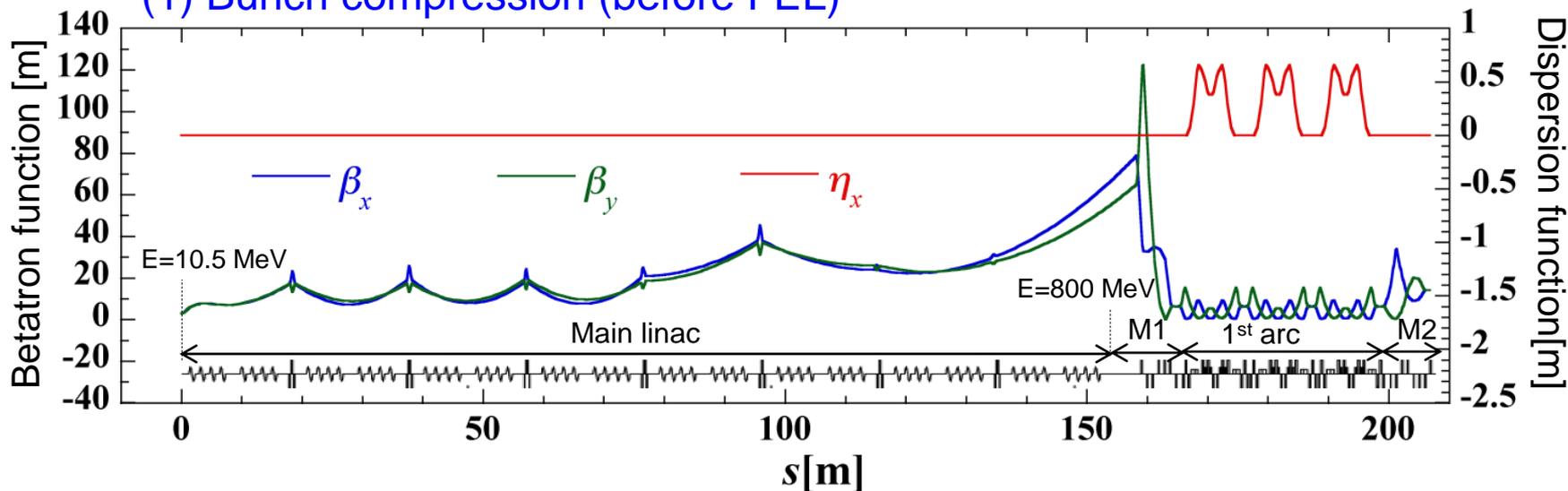


----- Projected normalized horizontal emittance

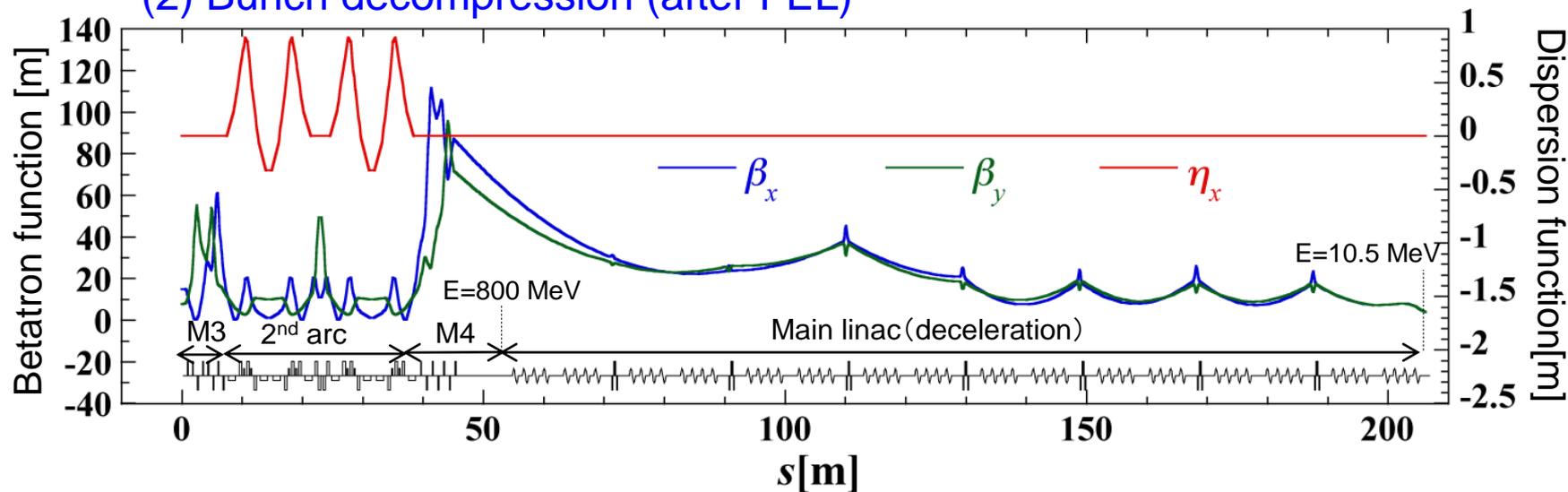
DBA lattice can well suppress CSR effects on ERL beam.

# Optics of Recirculation Loop

(1) Bunch compression (before FEL)



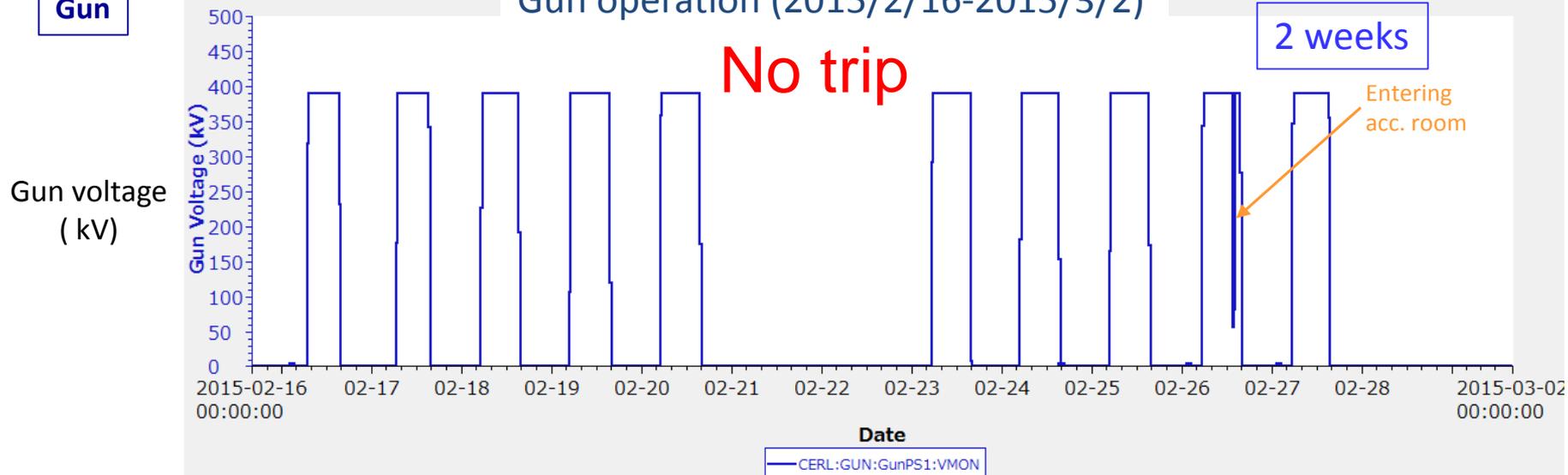
(2) Bunch decompression (after FEL)



# Operation of Gun & ML Cavities

Gun

Gun operation (2015/2/16-2015/3/2)



Main cavities  
(ML-1, ML-2)

ML operation (2015/2/16-2015/3/2)

